Datacon 2200 evo ^{hS}

Innovative Solution for Innovative Products

The Datacon 2200 evo ^{hS} die bonder for Multi Module Attach assembles all kinds of technologies on a tried-and-tested platform, enhanced with key features for higher bonding accuracy and lower cost of ownership.

Besides unbeaten flexibility and full customization possibilities, this evolutionary machine offers higher accuracy with long-term stability using a new camera system and thermal compensation algorithm, higher speed through a new image processing unit, and improved cleanroom capabilities.

Future Proof Equipment

Datacon 2200 evo goes hS!

Enhancements
· PLUS Accuracy
· PLUS Productivity
· PLUS Flexibility
· PLUS UPH

Features
· Multi-Chip Capability
· Flexibility for Customizing
· Open Platform Architecture

8 WEEKS LEAD TIME — 8W

HIGHEST OUTPUT — +30%

TOOL-TO-TOOL REPEATABILITY — T₂T

ACCURACY — 7μ

FLEXIBILITY

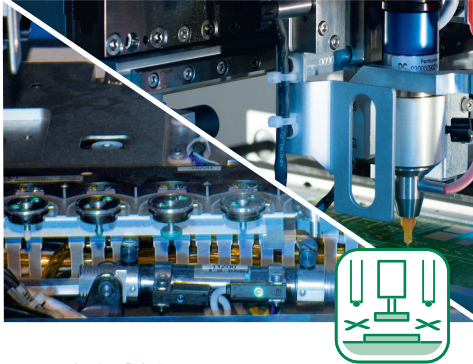**MULTI-CHIP**

Multi-Chip

· Fully automatic cycle for Multi-Chip production
· Up to 7 Pick & Place tools (optionally 14), 5 eject tools
· Pressure/time (Musashi®), Auger, Jetter type dispensers available
· Epoxy stamping option
· Filled and unfilled epoxy, wide viscosity range

Accuracy

· New high-speed image processing unit
· Full alignment & Bad mark search
· Pre-defined fiducial geometry & customized teaching

Pick & Place Head

· Die Attach, Flip Chip and Multi-Chip in one machine
· Die pick from: wafer, waffle pack, Gel-Pak®, feeder
· Die place to: substrate, boat, carrier, PCB, leadframe, wafer
· Hot and cold processes supported: epoxy, soldering, thermo-compression, eutectic
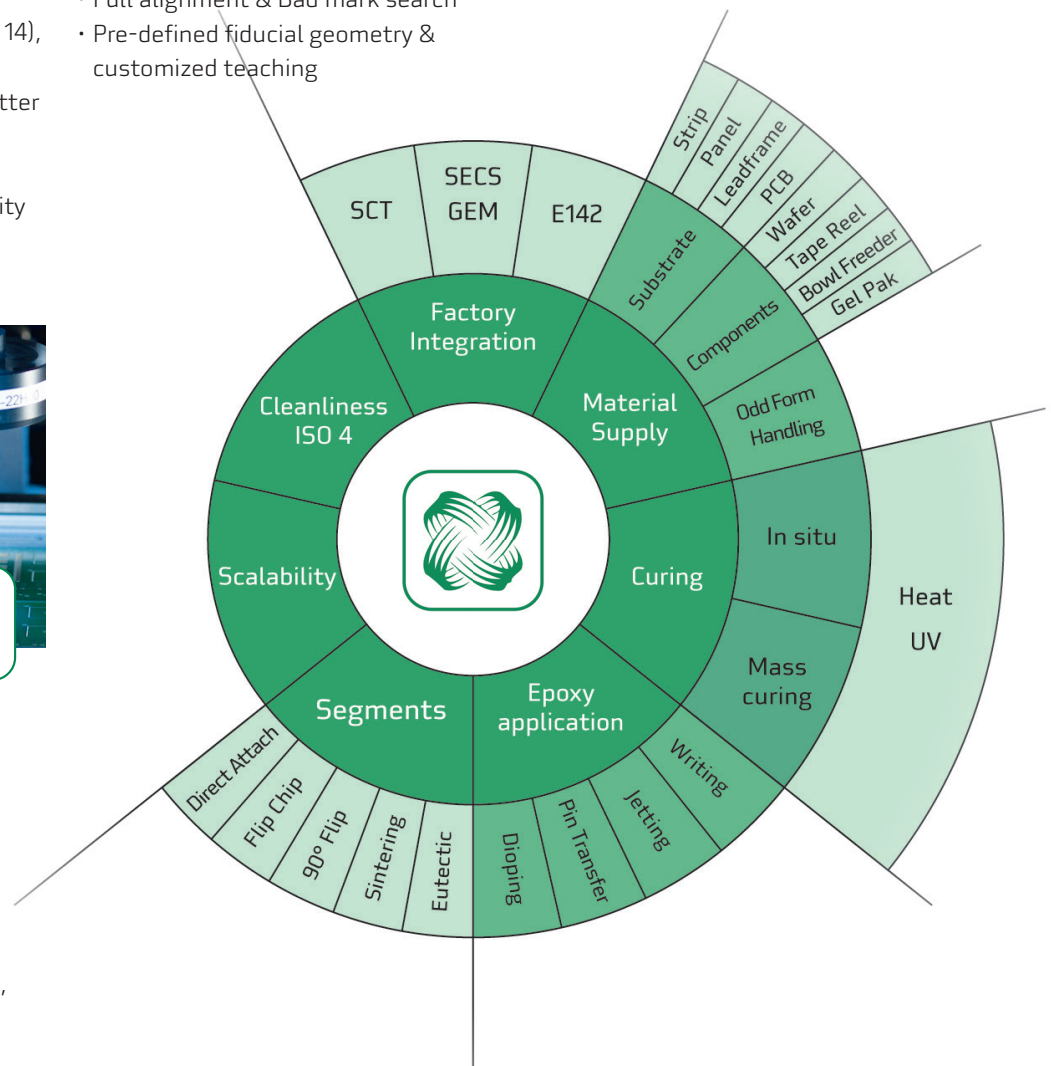
Performance

· X/Y placement accuracy: ± 7 µm @ 3s
· Theta placement accuracy: ± 0.10° @ 3s

Bond Heads

· Standard bond head 0° - 360° rotation
· Heated bond head (optional)

UPH

· up to 12000

Footprint/ Module

· L x D x H: 1160 mm x 1225 mm x 1750 mm
· Statistics
· Uptime > 98 %
· Yield > 99.95 %

Wafer

· Die size Die attach: 0.17 mm - 5 mm
· Die thickness: 0.05 mm - 2 mm
· Wafer size: 2" - 12" (50 mm - 300 mm)

Chip Trays

· Waffle pack / Gel-Pak® 2" x 2" and 4" x 4"
· JEDEC tray on request
· Substrates and Carriers

Substrate working range

· 13" x 8"(325 mm x 200 mm)